



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Shimizu et al.

Art Unit : 2814

Serial No. : 09/536898

Examiner : Louie, Wai Sing

Filed : March 28, 2000

Title : HYBRID INTEGRATED CIRCUIT DEVICE

Commissioner for Patents  
Washington, D.C. 20231RESPONSE

In response to the action mailed September 24, 2002, please amend the application as follows:

In the claims:

Please amend claims 1 and 15 as follows:

1. (Twice Amended) A hybrid integrated circuit device comprising:  
a hybrid integrated circuit substrate in which at least a surface is provided with insulation;  
at least a first electrode and at least a second electrode formed on said surface and being  
disposed to cover substantially the substrate;  
a light emitting element connected with the first and second electrodes, said first and  
second electrodes configured to reflect light;  
a seal which is disposed in a periphery of said substrate; and  
a transparent substrate which is fixed to said hybrid integrated circuit substrate via  
said seal to enclose the first and second electrodes and the light emitting element within a  
sealed space formed between said hybrid integrated circuit substrate and said transparent  
substrate.

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## CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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